

ABSTRACT OF THE DISCLOSURE

Disclosed is a film-forming method, comprising  
dispensing from a dispenser nozzle a coating solution,  
which is prepared by adding a solid component to a  
solvent and controlled to be spread on the substrate in  
a predetermined range, onto a target substrate to be  
processed while relatively moving the dispenser nozzle  
and the target substrate so as to form a liquid film on  
the entire surface of the target substrate, and  
arranging a sucking nozzle above and apart from the  
target substrate such that the sucking nozzle is not in  
contact with the surface of the liquid film so as to  
permit the sucking nozzle to suck the solvent vapor  
right under the sucking nozzle while moving the sucking  
nozzle relative to the target substrate, thereby  
removing the solvent from the liquid film and, thus,  
forming a coated film.